

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Components for low-voltage surge protection –
Part 341: Performance requirements and test circuits for thyristor surge
suppressors (TSS)**

**Composants pour parafoudres basse tension –
Partie 341: Exigences de performance et circuits d'essai pour parafoudres
à thyristor (TSS)**





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CONTENTS

| | |
|---|----|
| FOREWORD | 6 |
| 1 Scope | 8 |
| 2 Normative references | 8 |
| 3 Terms, definitions, abbreviated terms and symbols | 8 |
| 3.1 Parametric terms, letter symbols and definitions | 9 |
| 3.2 General terms | 9 |
| 3.3 Main terminal ratings | 9 |
| 3.4 Main terminal characteristics | 11 |
| 3.5 Additional and derived parameters | 12 |
| 3.6 Temperature related parameters | 12 |
| 3.7 Gate terminal parameters | 13 |
| 3.8 Abbreviated terms | 15 |
| 3.9 Circuit symbols | 15 |
| 4 TSS types | 16 |
| 5 Service conditions | 18 |
| 5.1 Normal service conditions | 18 |
| 5.2 Storage temperature range, $T_{\text{stg}\min}$ to $T_{\text{stg}\max}$ | 18 |
| 6 Mechanical requirements and identification | 18 |
| 6.1 Robustness of terminations | 18 |
| 6.2 Solderability | 18 |
| 6.3 Marking | 18 |
| 6.4 Documentation | 18 |
| 7 Standard test methods | 19 |
| 7.1 Failure rates | 19 |
| 7.2 Test conditions | 19 |
| 7.2.1 General | 19 |
| 7.2.2 Standard atmospheric conditions | 19 |
| 7.2.3 Measurement errors | 20 |
| 7.2.4 Measurement accuracy | 20 |
| 7.2.5 Designated impulse shape and values | 20 |
| 7.2.6 Multiple TSS | 20 |
| 7.2.7 Gated TSS testing | 20 |
| 7.3 Rating test procedures | 20 |
| 7.3.1 General | 20 |
| 7.3.2 Repetitive peak off-state voltage, V_{DRM} | 21 |
| 7.3.3 Repetitive peak on-state current, I_{TRM} | 21 |
| 7.3.4 Non-repetitive peak on-state current, I_{TSM} | 22 |
| 7.3.5 Non-repetitive peak pulse current, I_{PP} | 23 |
| 7.3.6 Repetitive peak reverse voltage, V_{RRM} | 24 |
| 7.3.7 Non-repetitive surge forward current, I_{FSM} | 24 |
| 7.3.8 Repetitive peak forward current, I_{FRM} | 24 |
| 7.3.9 Critical rate of rise of on-state current, di/dt | 25 |
| 7.4 Characteristic test procedures | 26 |
| 7.4.1 General | 26 |
| 7.4.2 Off-state current, I_D | 26 |
| 7.4.3 Repetitive peak off-state current, I_{DRM} | 27 |

| | | |
|--|---|----|
| 7.4.4 | Repetitive peak reverse current, I_{RRM} | 27 |
| 7.4.5 | Breakover voltage, $V_{(BO)}$ and current, $I_{(BO)}$ | 27 |
| 7.4.6 | On-state voltage, V_T | 29 |
| 7.4.7 | Holding current, I_H | 33 |
| 7.4.8 | Off-state capacitance, C_O | 34 |
| 7.4.9 | Forward voltage, V_F | 37 |
| 7.4.10 | Peak forward recovery voltage, V_{FRM} | 37 |
| 7.4.11 | Critical rate of off-state voltage rise, dv/dt | 38 |
| 7.4.12 | Variation of holding current with temperature | 38 |
| 7.4.13 | Gate-to-adjacent terminal peak off-state voltage and peak off-state gate current, V_{GDM}, I_{GDM} | 38 |
| 7.4.14 | Gate reverse current, adjacent terminal open, I_{GAO}, I_{GKO} | 39 |
| 7.4.15 | Gate reverse current, main terminals short-circuited, I_{GAS}, I_{GKS} | 40 |
| Annex A (informative) Common impulse waveshapes | | 41 |
| A.1 | General..... | 41 |
| A.2 | Types of impulse generator..... | 41 |
| A.3 | Impulse generator parameters | 41 |
| A.3.1 | Glossary of terms..... | 41 |
| A.3.2 | Virtual parameters | 42 |
| A.4 | Impulse generators typically used for surge protector testing | 44 |
| A.4.1 | General..... | 44 |
| A.4.2 | Impulse generators with a defined voltage waveform | 44 |
| A.4.3 | Impulse generators with a defined current waveform..... | 44 |
| A.4.4 | Generators with defined voltage and current waveforms | 45 |
| Annex B (informative) Glossary of IEC 60747-6 [10] thyristor terms | | 48 |
| B.1 | General..... | 48 |
| B.2 | Thyristor types | 48 |
| B.3 | Basic terms defining the static voltage-current characteristics of triode thyristors..... | 49 |
| B.4 | Basic terms defining the static voltage-current characteristics of diode thyristors..... | 51 |
| B.5 | Particulars of the static voltage-current characteristics of triode and diode thyristors..... | 52 |
| B.6 | Terms related to ratings and characteristics; principal voltages..... | 54 |
| B.7 | Terms related to ratings and characteristics; principal currents | 55 |
| B.8 | Terms related to ratings and characteristics; gate voltages and currents..... | 57 |
| B.9 | Terms related to ratings and characteristics; powers, energies and losses | 59 |
| B.10 | Letter symbols | 61 |
| B.10.1 | General..... | 61 |
| B.10.2 | List of letter symbols | 62 |
| Annex C (informative) Additional parametric tests | | 64 |
| C.1 | General..... | 64 |
| C.2 | Temperature derating..... | 64 |
| C.3 | Thermal resistance, R_{th} | 64 |
| C.4 | Transient thermal impedance, $Z_{th}(t)$ | 65 |
| C.5 | Gate reverse current, on-state, I_{GAT}, I_{GKT} | 66 |
| C.6 | Gate reverse current, forward conducting state, I_{GAF}, I_{GKF} | 67 |
| C.7 | Gate switching charge, Q_{GS} | 68 |
| C.8 | Peak gate switching current, I_{GSM} | 70 |

| | | |
|---------------------|--|----|
| C.9 | Gate-to-adjacent terminal breakdown voltage, $V_{GK(BO)}$, $V_{GA(BO)}$ | 71 |
| Annex D (normative) | Preferred values | 72 |
| D.1 | General..... | 72 |
| D.2 | $V_{(BO)}$ and V_{DRM} | 72 |
| D.3 | C_O , V_{DRM} and I_{PP} | 73 |
| D.4 | I_H | 74 |
| D.5 | I_{PP} and time to half value (duration) | 74 |
| Bibliography..... | | 75 |

| | |
|--|----|
| Figure 1 – Fixed voltage, two terminals: a) reverse blocking and b) reverse conducting | 15 |
| Figure 2 – Gated reverse blocking: a) P gate b) N gate and c) P & N gate | 16 |
| Figure 3 – Gated reverse conducting: a) P gate and b) N gate | 16 |
| Figure 4 – Bidirectional: a) 2 terminal fixed voltage and b) gated | 16 |
| Figure 5 – Switching quadrant characteristics: a) fixed-voltage TSS and b) gated TSS | 17 |
| Figure 6 – TSS non-switching characteristics: a) reverse blocking b) reverse conducting | 17 |
| Figure 7 – Test circuit for verifying repetitive peak off-state voltage (V_{DRM}) | 21 |
| Figure 8 – Test circuit for verifying repetitive peak on-state current, I_{TRM} | 21 |
| Figure 9 – Repetitive peak on-state current waveforms | 22 |
| Figure 10 – Test circuit for verifying non-repetitive peak on-state current, I_{TSM} | 23 |
| Figure 11 – Test circuit for verifying non-repetitive peak pulse current, I_{PP} | 24 |
| Figure 12 – Test circuit for verifying critical rate of rise of on-state current (di/dt) | 25 |
| Figure 13 – Half sine-wave di/dt test circuit | 26 |
| Figure 14 – Test circuit for off-state current, I_D at V_D | 27 |
| Figure 15 – Test circuit for breakdown, $V_{(BO)}$ and $I_{(BO)}$ and on-state voltage, V_T | 28 |
| Figure 16 – Voltage and current waveforms versus time for a fixed-voltage TSS showing switch-on, on-state and switch-off events | 28 |
| Figure 17 – Waveform expansions of Figure 16 | 30 |
| Figure 18 – Voltage and current waveforms versus time for a gated TSS showing switch-on, on-state and switch-off events | 31 |
| Figure 19 – Waveform expansions of Figure 18 | 32 |
| Figure 20 – Test circuit for holding current, I_H | 33 |
| Figure 21 – Test circuit for holding current with additional DC bias | 34 |
| Figure 22 – Test circuit for capacitance measurement | 34 |
| Figure 23 – Test circuit for capacitance measurement with external DC bias | 35 |
| Figure 24 – Test circuit for capacitance measurement of multi-terminal TSS | 36 |
| Figure 25 – Diode voltage and current waveforms versus time showing V_{FRM} and rising current di/dt | 37 |
| Figure 26 – Test circuit for exponential critical rate of off-state voltage rise, dv/dt | 38 |
| Figure 27 – Test circuit for gate-to-adjacent terminal peak off-state voltage and current, V_{GDM} and I_{GDM} | 39 |
| Figure 28 – Test circuit for gate reverse current, adjacent terminal open, I_{GAO} , I_{GKO} | 39 |
| Figure 29 – Test circuit for gate reverse current, main terminals short-circuited, I_{GAS} , I_{GKS} | 40 |
| Figure A.1 – Current or voltage impulse amplitude versus time showing a 10 % to 90 % T_1 front time and T_2 time to half value | 43 |

| | |
|--|----|
| Figure A.2 – Voltage impulse amplitude versus time showing a 30 % to 90 % T_1 front time and T_2 time to half value | 43 |
| Figure B.1 – Particulars of the static characteristic of unidirectional thyristors..... | 52 |
| Figure B.2 – Particulars of the static characteristic of bidirectional thyristors | 53 |
| Figure B.3 – a) Approximation of the on-state V_T - I_T characteristic b) Approximation of the reverse V_R - I_R characteristic | 60 |
| Figure C.1 – Test circuit for thermal resistance and impedance | 65 |
| Figure C.2 – Thermal impedance versus time | 66 |
| Figure C.3 – Test circuit for gate reverse current, on-state, I_{GAT} , I_{GKT} | 67 |
| Figure C.4 – Test circuit for gate reverse current, forward conducting state, I_{GAF} , I_{GKF} | 68 |
| Figure C.5 – Test circuit for gate switching current, gate switching charge and gate-to-adjacent terminal breakdown voltage, I_{GSM} , Q_{GS} , $V_{GK(BO)}$, $V_{GA(BO)}$ | 69 |
| Figure C.6 – Test circuit of an integrated gate diode TSS for gate switching current, gate switching charge and gate-to-adjacent terminal breakdown voltage I_{GSM} , Q_{GS} , $V_{GK(BO)}$, $V_{GA(BO)}$ | 70 |
| Figure C.7 – Overall and expanded clamping waveforms for a P-type gate TSS showing $V_{GK(BO)}$ and Q_{GS} measurement ($dI_K/dt = 10 \text{ A}/\mu\text{s}$, $V_{GG} = -72 \text{ V}$) | 71 |
| Figure D.1 – $V_{(BO)}/V_{DRM}$ ratio against V_{DRM} | 72 |
| Figure D.2 – $V_{(BO)}$ vs V_{DRM} | 73 |
| Figure D.3 – Capacitance variation with DC bias..... | 73 |
| Figure D.4 – I_{PP} versus Duration for various 10/1 000 current ratings | 74 |
| Table 1 – Types of TSS | 17 |
| Table 2 – Breakover ramp rate test values | 29 |
| Table A.1 – Voltage impulse generators..... | 44 |
| Table A.2 – Current impulse generators | 45 |
| Table A.3 – Voltage and current impulse generators | 46 |
| Table A.4 – Other voltage and current impulse generators | 47 |
| Table B.1 – Additional general subscripts | 61 |
| Table B.2 – Principal voltages, anode-cathode voltages..... | 62 |
| Table B.3 – Principal currents, anode currents, cathode currents | 62 |
| Table B.4 – Gate voltages..... | 63 |
| Table B.5 – Gate currents | 63 |
| Table B.6 – Sundry quantities | 63 |
| Table B.7 – Power loss | 63 |

INTERNATIONAL ELECTROTECHNICAL COMMISSION

COMPONENTS FOR LOW-VOLTAGE SURGE PROTECTION –

Part 341: Performance requirements and test circuits for thyristor surge suppressors (TSS)

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International Standard IEC 61643-341 has been prepared by subcommittee 37B, Components for low-voltage surge protection, of IEC technical committee 37: Surge arresters.

This second edition of IEC 61643-341 cancels and replaces the first edition published in 2001. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition: Addition of performance values.

The text of this standard is based on the following documents:

| FDIS | Report on voting |
|--------------|------------------|
| 37B/218/FDIS | 37B/220/RVD |

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of IEC 61643 series, under the general title *Components for low-voltage surge protective devices*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

COMPONENTS FOR LOW-VOLTAGE SURGE PROTECTION –

Part 341: Performance requirements and test circuits for thyristor surge suppressors (TSS)

1 Scope

This part of IEC 61643 specifies standard test circuits and methods for thyristor surge suppressor (TSS) components. These surge protective components, SPCs, are specially formulated thyristors designed to limit overvoltages and divert surge currents by clamping and switching actions. These SPCs are used in the construction of surge protective devices (SPDs) and equipment used in Information & Communications Technologies (ICT) networks with voltages up to AC 1 000 V and DC 1 500 V. This document is applicable to gated or non-gated TSS components with third quadrant (-v and -i) characteristics of blocking, conducting or switching.

This document contains information on

- terminology;
- letter symbols;
- essential ratings and characteristics;
- rating verification and characteristic measurement;

This document does not apply to the conventional three-terminal thyristors as covered by IEC 60747-6.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050-521, *International Electrotechnical Vocabulary – Chapter 521: Semiconductor devices and integrated circuits*

IEC 60068-2-20:2008, *Environmental testing – Part 2-20: Tests – Test T: Test methods for solderability and resistance to soldering heat of devices with leads*

3 Terms, definitions, abbreviated terms and symbols

For the purposes of this document, the following terms and definitions apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

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